

SOT754-1

plastic thin fine-pitch ball grid array package; 256 balls; body
15 x 15 x 0.8 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA256
Package type industry code	TFBGA256
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-216
Mounting method type	S (surface mount)
Issue date	14-1-2002

Table 1. Package summary

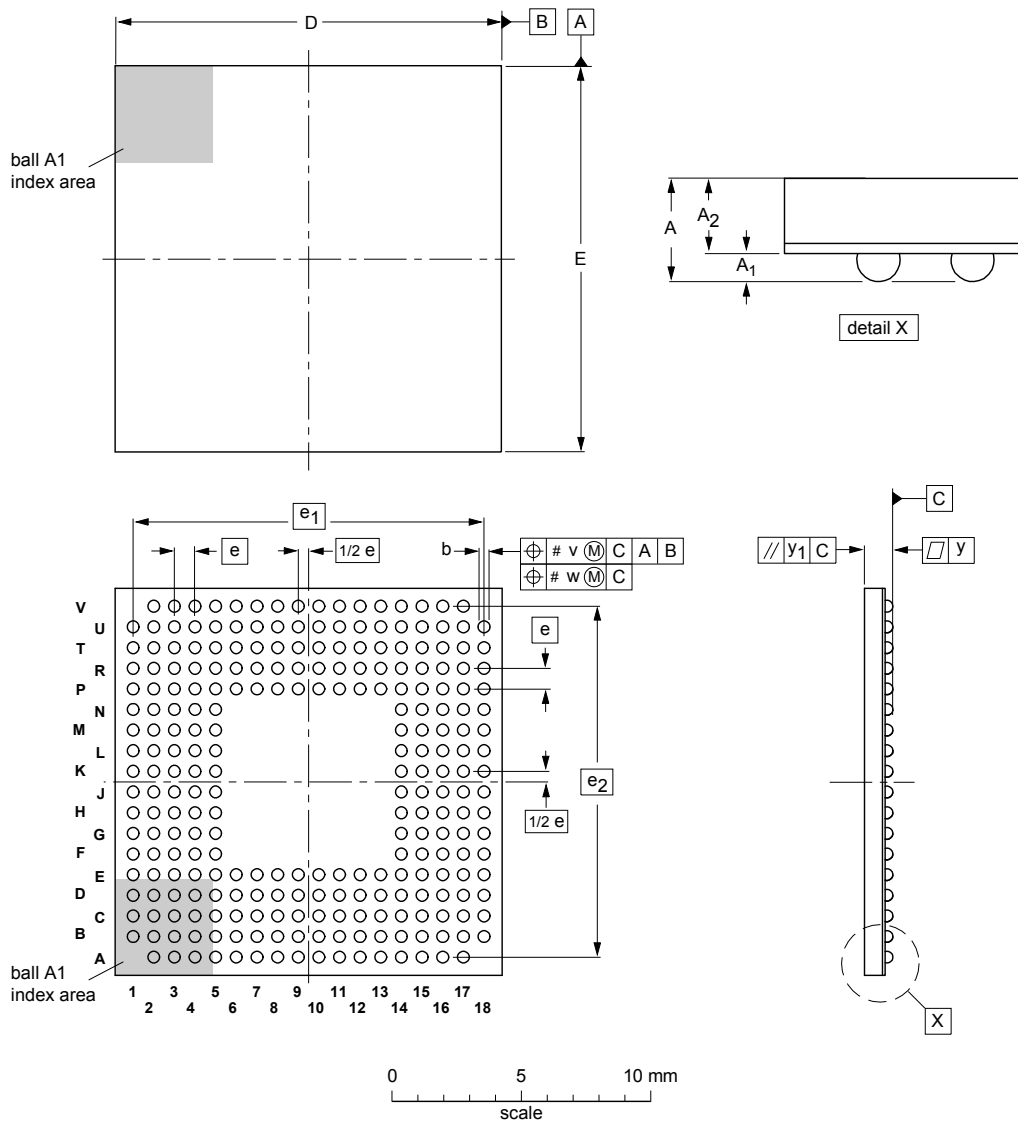
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	14.9	-	15	15.1	mm
E	package width	14.9	-	15	15.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.75	-	0.8	0.85	mm
e	nominal pitch	-	-	0.8	-	mm
n ₂	actual quantity of termination	-	-	256	-	



2. Package outline

TFBGA256: plastic thin fine-pitch ball grid array package; 256 balls; body 15 x 15 x 0.8 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	1.2	0.35 0.25	0.85 0.75	0.5 0.4	15.1 14.9	15.1 14.9	0.8	13.6	13.6	0.15	0.08	0.12	0.1

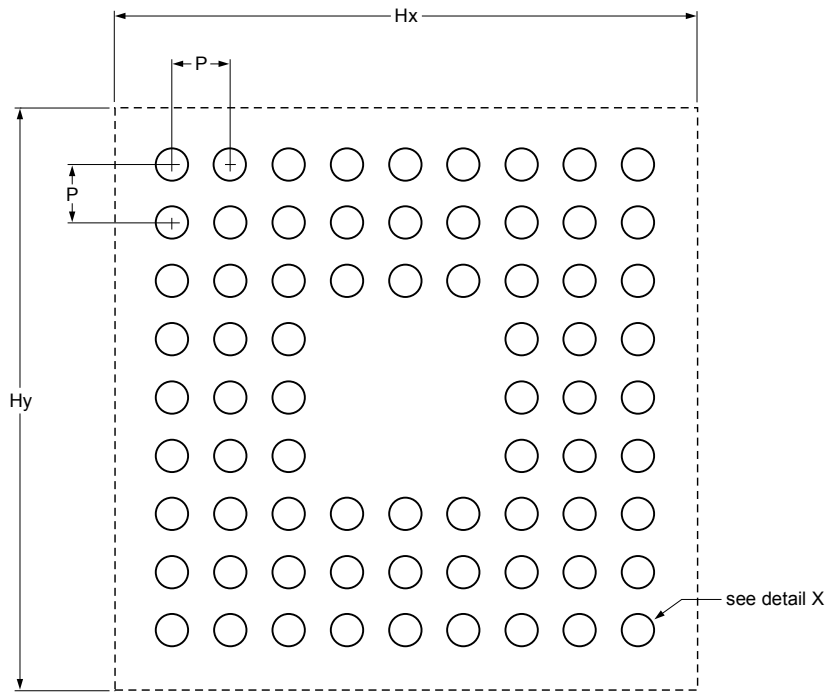
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT754-1	---	MO-216	---			02-01-14

Fig. 1. Package outline TFBGA256 (SOT754-1)




3. Soldering

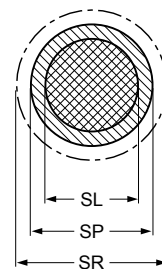
Footprint information for reflow soldering of TFBGA256 package

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Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.80	0.330	0.400	0.480	15.575	15.575

sot754-1_fr

Fig. 2. Reflow soldering footprint for TFBGA256 (SOT754-1)

4. Legal information

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Date of release: 8 February 2016
